

18. *the apparatus 1*  
A polisher according to Claim 17 and having a layer of liquid between said window and said wafer during operation of said optical thickness measuring unit.

*Sub 19*  
19. A polisher according to Claim 17 wherein said optical thickness measuring unit includes:

an illumination optical unit for directing light towards said wafer;

an imaging unit for imaging said top layer;

a spectrophotometric detector; and

separation optics for providing light reflected from said wafer separately to said imaging unit and to said spectrophotometric detector, the separation optics comprising an objective lens, a pinhole mirror and first and second relay lenses wherein said first relay lens focuses the light passing through said pinhole mirror onto said spectrophotometric detector and wherein said second relay lens focuses the light reflected from said pinhole mirror onto said imaging unit.

#### DELETION OF INVENTORS

In view of the invention being pursued in this continuing application, the following persons which are named on the Declaration For Patent Application in the parent application should be deleted because they are not inventors in this continuation application: Eran Dvir; Eli Haimovich; and Benjamin Shulman.

#### REMARKS

This is a continuation application of Serial No. 08/497,382, filed June 29, 1995.